

Advanced Packaging Update: Market and Technology Trends

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This issue of the Advanced Packaging Update features a detailed financial analysis of the OSATs and an outlook for the remainder of 2019. The impact of trade friction on the electronics industry is analyzed. TSMC and Samsung foundry package offerings from mobile to high performance are described. A unit forecast for BGAs and CSPs by package construction is provided. The CSP market is divided into laminate and leadframe (QFN) substrates. Unit growth projections and future trends for package-on-package (PoP) are included. Estimates of the market for each package type are based on input from captive as well as merchant assembly operations.

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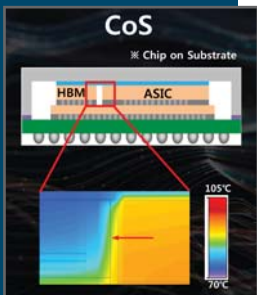
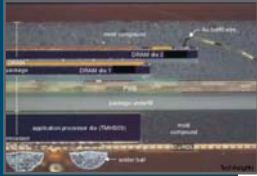
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4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com